

Quarterly Reliability Monitoring Results

Quarters: Q3/2021 to Q4/2022

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number						
		PESD5V0S1UB-Q						
		Part Description						
		Nexperia DHAM Protection						
		SMD package						
		Test Conditions	Duration	# Lots	# Quantity	# Rejects		
	TEST							
	Pre- and Post-Stress							
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
		JESD22-A113						
		Bake Tamb = 125 °C	24 hours					
,, , ,	PC Preconditioning	Soak Tamb = 85 °C, RH = 85% Reflow soldering	168 hours 3 cycles	400	24620			
# A1	Preconditioning		3 Cycles	438	24630	0		
	UTDD	MIL-STD-750-1						
	HTRB	M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet						
# B1	Bias	reverse voltage	1000 hours	166	10040	0		
# DI	Bid3	Teverse voltage	1000 110015	100	10040	U		
	тс	JESD22-A104						
# A4	Temperature Cycling	-65 °C to Timax, not to exceed 150°C	1000 cycles	131	7760	0		
,,,,,	. , , ,	, , , , , , , , , , , , , , , , , , ,	1000 cycles	131	7700	•		
	UHAST	JESD22-A118						
# A3 or	Unbiased HAST	Tamb = 130 °C, RH = 85 %	— 96 hours	131	7760	0		
		JESD22-A102						
	AC	Tamb = 121 °C, RH = 100 %						
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)						
	H3TRB	JESD22-A101						
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of						
# A2 alt	Temperature Reverse Bias	rated reverse voltage ^[1]	1000 hours	131	7760	0		
		MIL-STD-750 Method 1037						
	IOL	ton = toff, devices powered to insure ΔTj =						
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	n.a.	n.a.	n.a.		
	RSH	JESD22-A111				_		
# C8	Resistance to Solder Heat	260 °C ± 5 °C	10 s	45	1350	0		
" 610	SD Coldorability	1 STD 003			1110			
# C10	Solderability	J-STD-002		111	1110	0		

^[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Protection	10040	0	0,42	2,36E+09

^{© 2023} Nexperia B.V.

All information hereunder is per Nexperia's best knowledge. This document does not provide for any representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.

nexperia.com